Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP A-MSR20-21 Router (JD663B)
HP A-MSR50-40 Router (JD433A)
HP A-MSR50-60 Router (JF231A)
HP A-MSR50-40 DC Router (JF285A)
HP A-MSR50-60 DC Router (JF640A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	6
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		2
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		7
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

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Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 1, and then remove mounting angle 1.
2. Unscrew the screws on filler panel 2, and then remove filler panel 2.
3. Unscrew the screws on card 3, and then remove card 3.
4. Unscrew the screws on card 4, and then remove card 4.
5. Unscrew the screws on fan module frame 5, and then remove fan module frame 5.
6. Unscrew the screws on card 6, and then remove card 6.
7. Unscrew the screws on filler panel 7, and then remove filler panel 7.
8. Unscrew the screws on power supply 8, and then remove power supply 8.
9. Remove film 9 from subrack.
10. Unscrew the screws on bracket 10, and then remove bracket 10.
11. Remove film 11 from plastic panel 12.
12. Remove plastic panel 12 from subrack.
13. Remove guide rail 13 from subrack.
14. Remove shielding finger 15 from subrack..
15. Remove all of the labels.
16. Unscrew the screws on cabling rack 1-2 from mounting angle 1-1.
17. Remove film 2-2 from filler panel 2-1.
18. Remove all of the shielding finger 2-3 from filler panel 2-1.
19. Unscrew the screws on PCB 3-5, and then remove PCB 3-5.
20. Unscrew the screws on PCB 3-4, and then remove PCB 3-4.
21. Remove all of the shielding finger 3-4.
22. Remove film 3-2 from card 3-1.
23. Unscrew the screws on card 16, and then remove card 16.
24. Unscrew the screws on filler panel 18, and then remove filler panel 18.
25. Unscrew the screws on guide rail 17, and then remove guide rail 17.
26. Remove PCB 4-2.
27. Unscrew the screws on PCB 4-1, and then remove PCB 4-1.
28. Unscrew the screws on PCB 4-3, and then remove PCB 4-3.
29. Remove all of the cables.
30. Remove all of the labels.
31. Unscrew the screws on fixing bracket 5-7, and then remove fixing bracket 5-7.
32. Unscrew the screws on PCB 5-6, and then remove PCB 5-6.
33. Unscrew the screws on fan 5-8, and then remove fan 5-8.
34. Unscrew the screws on fan 5-5, and then remove fan 5-5.

35. Remove all of the shielding finger 5-4.
36. Unscrew the nut on pulled handle 5-2, and then remove pulled handle 5-2.
37. Remove film 5-3.
38. Unscrew the screws on PCB 6-3, and then remove PCB 6-3.
39. Unscrew the screws on PCB 6-4, and then remove PCB 6-4.
40. Remove PCB 6-2.
41. Unscrew the screws on PCB 6-1, and then remove PCB 6-1.
42. Remove shielding finger 6-6.
43. Remove shielding finger 6-5.
44. Remove film 7-2 from filler panel 7-1.
45. Remove all of the shielding finger 7-3 from filler panel 7-1.
46. Unscrew the screws on PCB 10-2, and then remove PCB 10-2.
47. Remove all of the shielding finger 10-3.
48. Remove all of the shielding finger 13-2 from guide rail 13-1.
49. Remove all of the shielding finger 15-4.
50. Remove film 15-1 from front panel 15-3.
51. Remove film 15-2 from front panel 15-3.
52. Unscrew the screws on PCB 16-1, and then remove PCB 16-1.
53. Remove Insulating pad 16-3 from front panel 16-2.
54. Remove all of the shielding finger 16-4.
55. Remove shielding finger 17-2.
56. Remove shielding finger 18-2 from filler panel 18-1.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

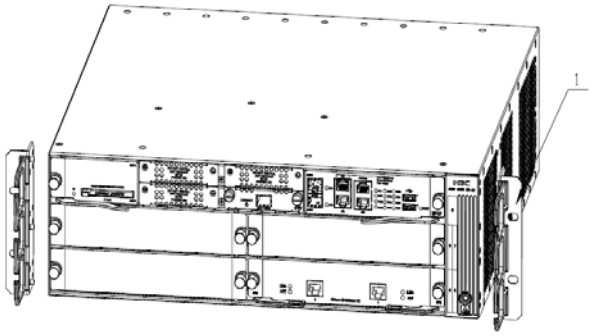

Figure 1 Remove mounting angle 1

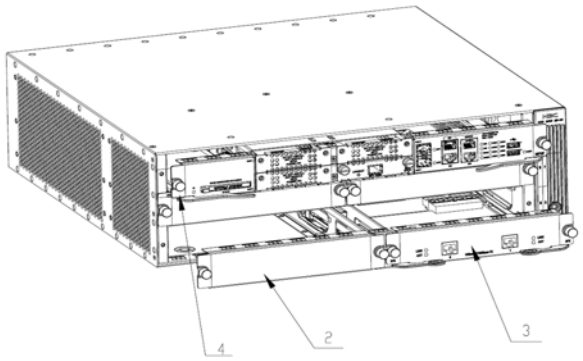

Figure 2 Treatments to the card

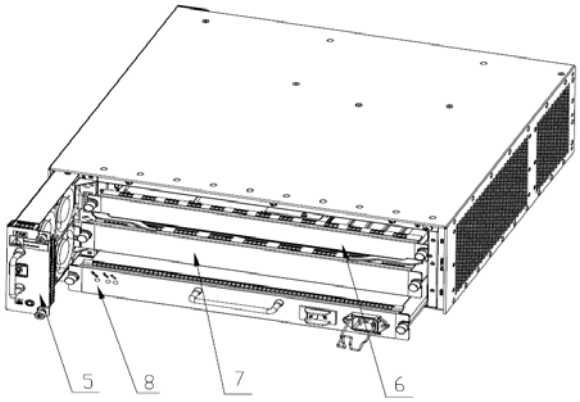

Figure 3 Treatments to the power supply and fan frame

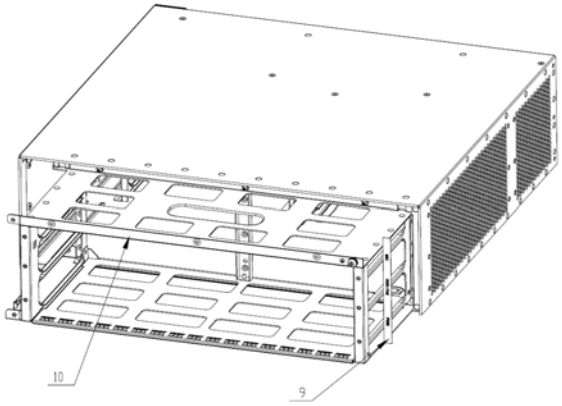

Figure 4 Treatments to the bracket

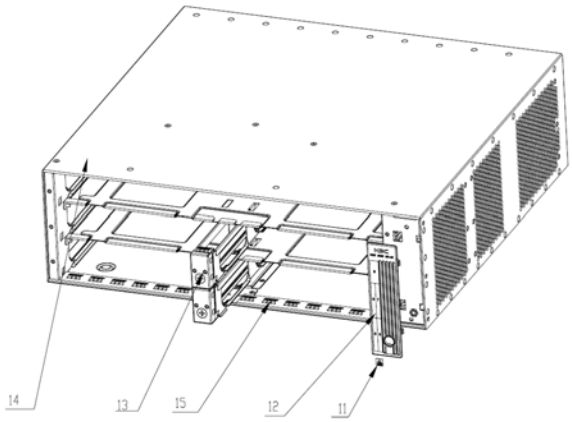

Figure 5 Treatments to guide rail and plastic panel

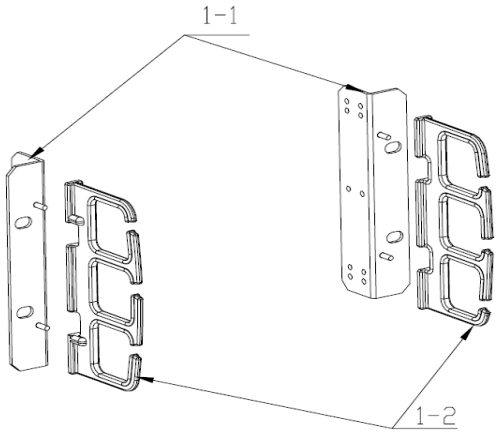

Figure 6 Treatments to mounting angle 1

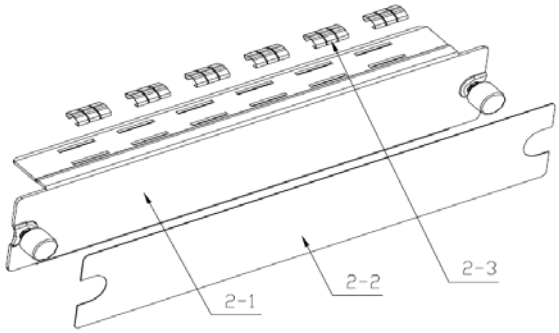

Figure 7 Treatments to filler panel 2

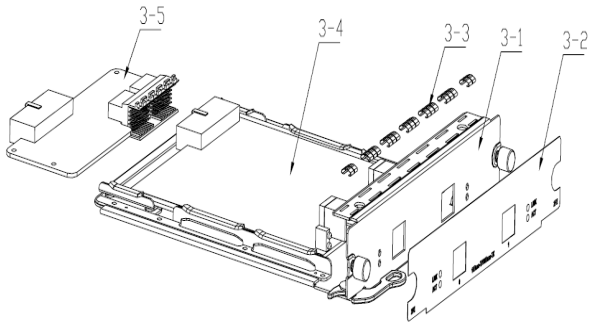

Figure 8 Treatments to card 3

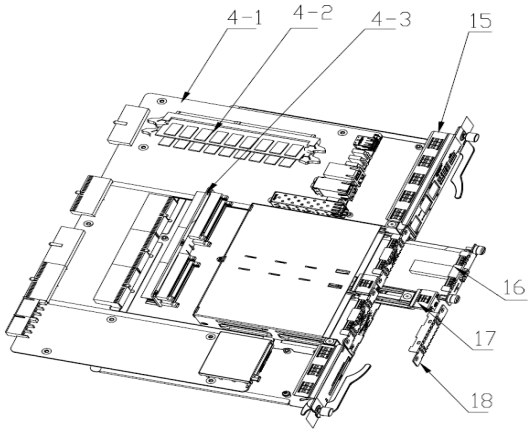

Figure 9 Treatments to card 4

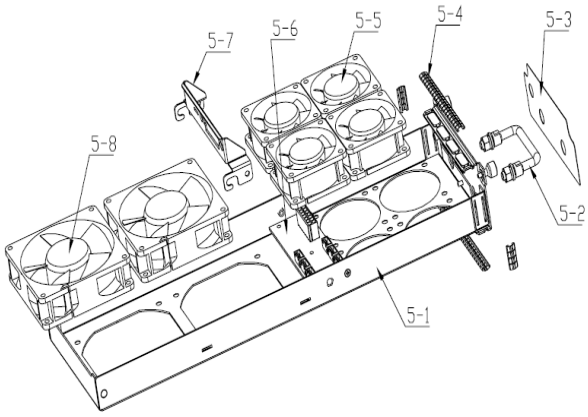

Figure 10 Treatments to fan module frame 5

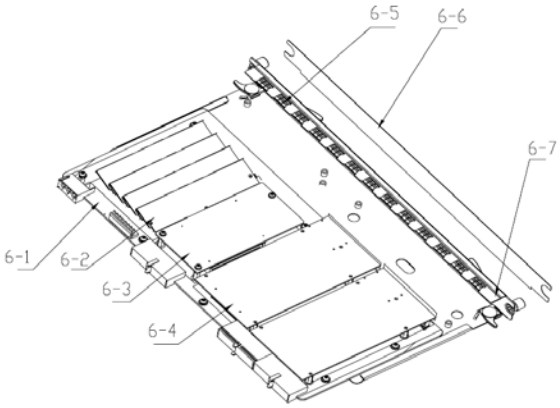

Figure 11 Treatments to card 6

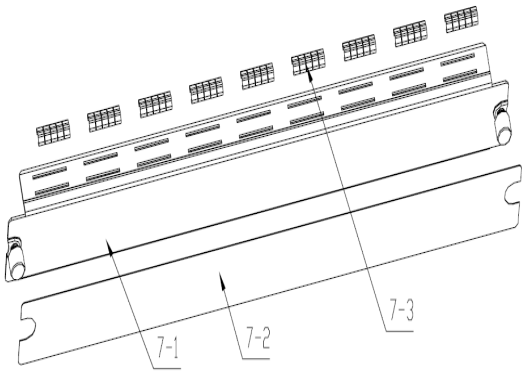

Figure 12 Treatments to filler panel 7

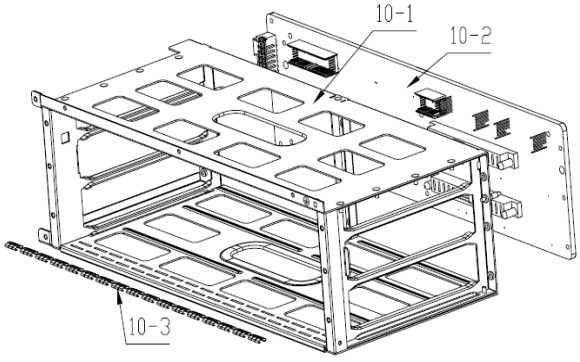

Figure 13 Treatments to bracket 10

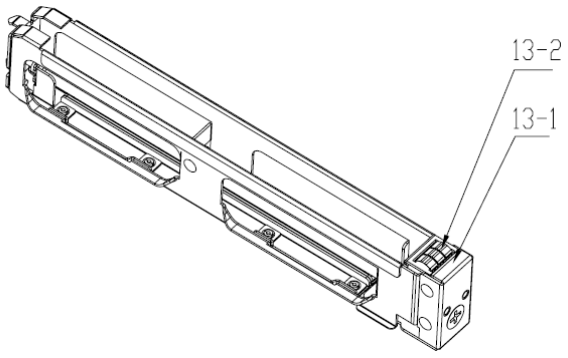

Figure 14 Treatments to guide rail 13

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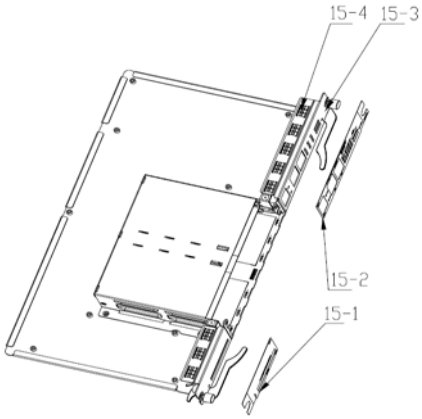

Figure 15 Treatments to front panel 15

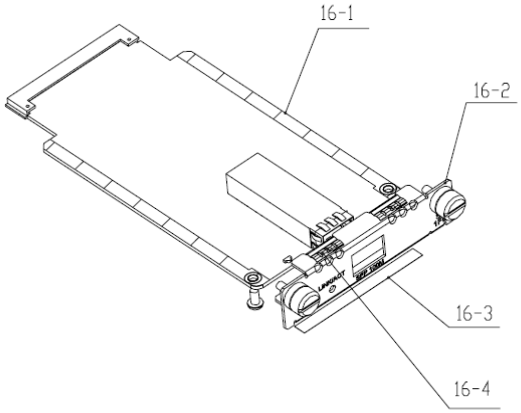

Figure 16 Treatments to card 16

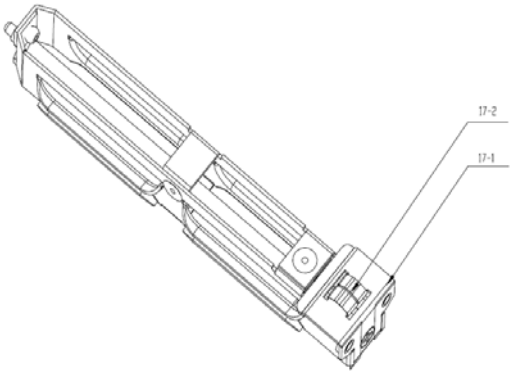

Figure 17 Treatments to guide rail 17

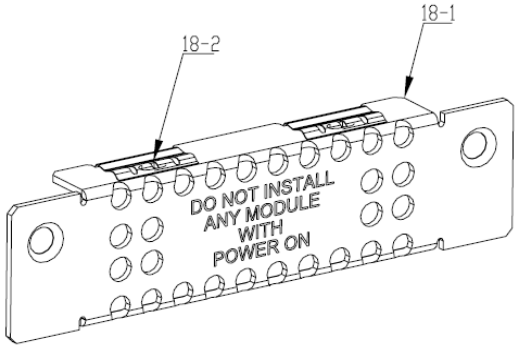

Figure 18 Treatments to filler panel 18